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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	8272
Number of Logic Elements/Cells	74448
Total RAM Bits	6045696
Number of I/O	996
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1704-BBGA, FCBGA
Supplier Device Package	1704-FCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp70-5ffg1704c

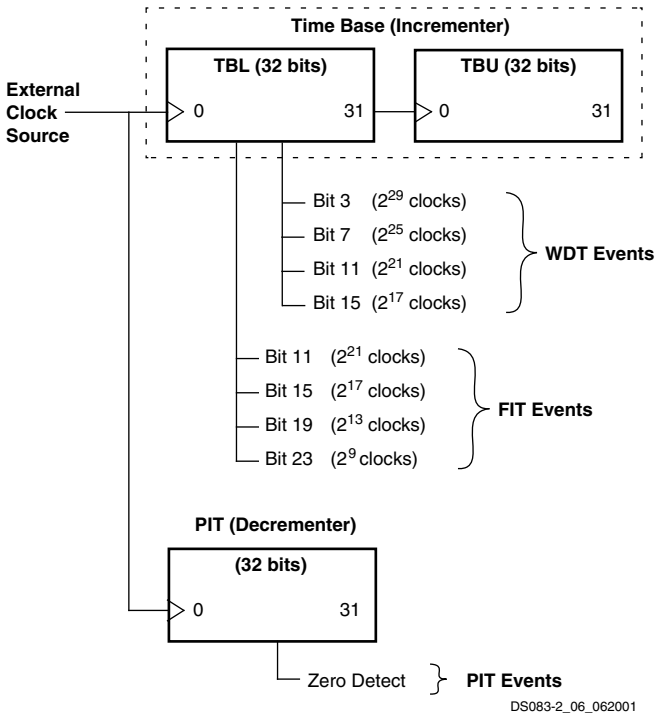

Figure 17: **Relationship of Timer Facilities to Base Clock**

Interrupts

The PPC405 provides an interface to an interrupt controller that is logically outside the PPC405 core. This controller combines the asynchronous interrupt inputs and presents them to the embedded core as a single interrupt signal. The sources of asynchronous interrupts are external signals, the JTAG/debug unit, and any implemented peripherals.

Debug Logic

All architected resources on the embedded PPC405 core can be accessed through the debug logic. Upon a debug event, the PPC405 core provides debug information to an external debug tool. Three different types of tools are supported depending on the debug mode: ROM monitors, JTAG debuggers, and instruction trace tools.

In internal debug mode, a debug event enables exception-handling software at a dedicated interrupt vector to take over the CPU core and communicate with a debug tool. The debug tool has read-write access to all registers and can set hardware or software breakpoints. ROM monitors typically use the internal debug mode.

In external debug mode, the CPU core enters stop state (stops instruction execution) when a debug event occurs. This mode offers a debug tool read-write access to all registers in the PPC405 core. Once the CPU core is in stop state, the debug tool can start the CPU core, step an instruction, freeze the timers, or set hardware or software break points. In addition to CPU core control, the debug logic is capable of writing instructions into the instruction cache, eliminating the need for external memory during initial board bring-up. Communication to a debug tool using external debug mode is through the JTAG port.

Debug wait mode offers the same functionality as external debug mode with one exception. In debug wait mode, the CPU core goes into wait state instead of stop state after a debug event. Wait state is identical to stop state until an interrupt occurs. In wait state, the PPC405 core can vector to an exception handler, service an interrupt and return to wait state. This mode is particularly useful when debugging real time control systems.

Real-time trace debug mode is always enabled. The debug logic continuously broadcasts instruction trace information to the trace port. When a debug event occurs, the debug logic signals an external debug tool to save instruction trace information before and after the event. The number of instructions traced depends on the trace tool.

Debug events signal the debug logic to stop the CPU core, put the CPU core in debug wait state, cause a debug exception or save instruction trace information.

Big Endian and Little Endian Support

The embedded PPC405 core supports big endian or little endian byte ordering for instructions stored in external memory. Since the PowerPC architecture is big endian internally, the ICU rearranges the instructions stored as little endian into the big endian format. Therefore, the instruction cache always contains instructions in big endian format so that the byte ordering is correct for the execution unit. This feature allows the 405 core to be used in systems designed to function in a little endian environment.

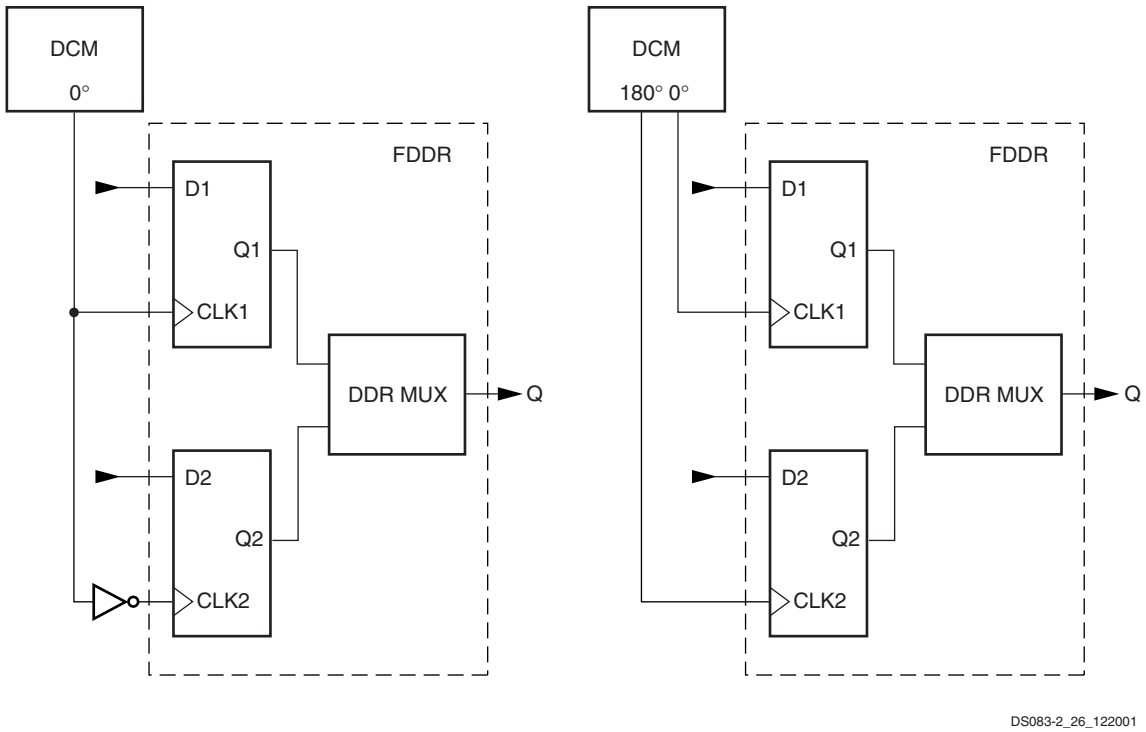

Figure 20: **Double Data Rate Registers**

This DDR mechanism can be used to mirror a copy of the clock on the output. This is useful for propagating a clock along the data that has an identical delay. It is also useful for multiple clock generation, where there is a unique clock driver for every clock load. Virtex-II Pro devices can produce many copies of a clock with very little skew.

Each group of two registers has a clock enable signal (ICE for the input registers, OCE for the output registers, and TCE for the 3-state registers). The clock enable signals are active High by default. If left unconnected, the clock enable for that storage element defaults to the active state.

Each IOB block has common synchronous or asynchronous set and reset (SR and REV signals). Two neighboring IOBs have a shared routing resource connecting the ICLK and OTCLK pins on pairs of IOBs. If two adjacent IOBs using DDR registers do not share the same clock signals on their clock pins (ICLK1, ICLK2, OTCLK1, and OTCLK2), one of the clock signals will be unroutable.

The IOB pairing is identical to the LVDS IOB pairs. Hence, the package pin-out table can also be used for pin assignment to avoid conflict.

SR forces the storage element into the state specified by the SRHIGH or SRLOW attribute. SRHIGH forces a logic 1. SRLOW forces a logic “0”. When SR is used, a second input (REV) forces the storage element into the opposite state. The reset condition predominates over the set condition. The initial state after configuration or global initialization state is defined by a separate INIT0 and INIT1 attribute. By default, the SRLOW attribute forces INIT0, and the SRHIGH attribute forces INIT1.

For each storage element, the SRHIGH, SRLOW, INIT0, and INIT1 attributes are independent. Synchronous or asynchronous set / reset is consistent in an IOB block.

All the control signals have independent polarity. Any inverter placed on a control input is automatically absorbed.

Each register or latch, independent of all other registers or latches, can be configured as follows:

- No set or reset
- Synchronous set
- Synchronous reset
- Synchronous set and reset
- Asynchronous set (preset)
- Asynchronous reset (clear)
- Asynchronous set and reset (preset and clear)

The synchronous reset overrides a set, and an asynchronous clear overrides a preset.

Refer to Figure 21.

Date	Version	Revision
03/24/03	2.5.1	• Table 10: Corrected I/O standard names SSTL18_I and SSTL18_II to SSTL18_I_DCI and SSTL18_II_DCI respectively. • Figure 61, text below: Corrected wording of criteria for clock switching.
05/27/03	2.6	• Removed Compatible Output Standards and Compatible Input Standards tables. • Added new Table 12, Summary of Voltage Supply Requirements for All Input and Output Standards. This table replaces deleted I/O standards tables. • Corrected sentence in section Input/Output Individual Options, page 27, to read “The optional weak-keeper circuit is connected to each *user I/O pad*.” • Added section Rules for Combining I/O Standards in the Same Bank, page 29.
06/02/03	2.7	• Added four Differential Termination I/O standards to Table 9 and Table 12. • Added section On-Chip Differential Termination and Figure 31, page 34.
08/25/03	2.7.1	• Added footnote referring to XAPP659 to 3.3V I/O callouts in Table 8 and Table 12.
09/10/03	2.8	• Section Configuration, page 56: Added text indicating that the mode pins M0-M2 must be held to a constant DC level during and after configuration.
10/14/03	2.9	• Deleted section Functional Description: RocketIO Multi-Gigabit Transceiver (MGT), page 10. Added section Local Clocking, page 51. • Sections Slave-Serial Mode and Master-Serial Mode, page 56: Changed "rising" to "falling" edge with respect to DOUT. • Table 8, page 24 and Table 10, page 25: Corrected Input V_{REF} for HSTL_III-IV_18 from 1.08V to 1.1V.
12/10/03	3.0	• XC2VP2 through XC2VP70 speed grades -5, -6, and -7, and XC2VP100 speed grades -5 and -6, are released to **Production status**.
02/19/04	3.1	• Section BUFGMUX, page 50: Corrected the definition of the "presently selected clock" to be I0 or I1. Corrected signal names in Figure 61 and associated text from CLK0 and CLK1 to I0 and I1.
03/09/04	3.1.1	• Recompiled for backward compatibility with Acrobat 4 and above. No content changes.
04/22/04	3.2	• Section Clock De-skew, page 52: Removed reference to CLK2X as an option for DCM clock feedback.
06/30/04	4.0	Merged in DS110-2 (Module 2 of Virtex-II Pro X data sheet). Separate RocketIO and RocketIO X sections created.
11/17/04	4.1	• Figure 11, page 12: Corrected figure by removing coupling capacitors from input. • Section Rules for Combining I/O Standards in the Same Bank, page 29: Corrected I/O standard in the first example from LVDS_25_DCI to LVDS_25.
03/01/05	4.2	• Reassigned heading hierarchies for better agreement with content. • Table 7: Corrected VCCAUXTX and VCCAUXRX to AVCCAUXTX and AVCCAUXRX respectively. • Table 9: Corrected V_{OD} (output voltage) range for LVDSEXT_25. • Table 25: Corrected SelectRAM+ memory available for XC2VPX70 device. • Table 33: Updated configuration default bitstream lengths.
06/20/05	4.3	*No changes in Module 2 for this revision.*
09/15/05	4.4	• Table 1: Deleted SONET OC-192 protocol. • Table 3: Deleted RocketIO X primitives for SONET OC-192, 10 Gbit Ethernet, and Xilinx 10G (Aurora) protocols. • Changed all instances of 10.3125 Gb/s to 6.25 Gb/s. • Table 7: Changed RocketIO X VCCAUXRX from 1.5V globally to 1.5V for 8B/10B encoding, 1.8V for all other encoding protocols.

Table 31: **RocketIO X RXUSRCLK2 Switching Characteristics *(Continued)***

		Speed Grade			
Description	**Symbol**	**-7**	**-6**	**-5**	**Units**
RXDEC64B66BUSE RXDEC8B10BUSE control input	$T_{GCCK\_}RDEC/T_{GCCK\_}RDEC$				ns, min
RXDESCRAM64B66BUSE control input	$T_{GCCK\_}RDES/T_{GCCK\_}RDES$				ns, min
RXINTDATAWIDTH control input	$T_{GCCK\_}RIDATW/T_{GCCK\_}RIDATW$				ns, min
RXSLIDE control input	$T_{GCCK\_}RXSLIDE/T_{GCCK\_}RXSLIDE$				ns, min
Clock to Out					
PMARXLOCK status output	$T_{GCKST\_}PLCK$				ns, max
RXNOTINTABLE status outputs	$T_{GCKST\_}RNIT$				ns, max
RXDISPERR status outputs	$T_{GCKST\_}RDERR$				ns, max
RXCHARISCOMMA status outputs	$T_{GCKST\_}RCMCH$				ns, max
RXREALIGN status output	$T_{GCKST\_}ALIGN$				ns, max
RXCOMMADET status output	$T_{GCKST\_}CMDT$				ns, max
RXLOSSOFSYNC status outputs	$T_{GCKST\_}RLOS$				ns, max
RXCLKCORCNT status outputs	$T_{GCKST\_}RCCCNT$				ns, max
RXBUFSTATUS status outputs	$T_{GCKST\_}RBSTA$				ns, max
CHBONDDONE status output	$T_{GCKST\_}CHBD$				ns, max
RXCHARISK status outputs	$T_{GCKST\_}RKCH$				ns, max
RXRUNDISP status outputs	$T_{GCKST\_}RRDIS$				ns, max
RXDATA data outputs	$T_{GCKDO\_}RDAT$				ns, max
Clock					
RXUSRCLK2 minimum pulse width, High	T_{RX2PWH}				ns, min
RXUSRCLK2 minimum pulse width, Low	T_{RX2PWL}				ns, min

Table 32: **RocketIO RXUSRCLK2 Switching Characteristics**

		Speed Grade			
Description	**Symbol**	**-7**	**-6**	**-5**	**Units**
Setup and Hold Relative to Clock (RXUSRCLK2)					
RXRESET control input	$T_{GCCK\_}RRST/T_{GCKC\_}RRST$	0.02/ 0.00	0.02/ 0.00	0.02/ 0.00	ns, min
RXPOLARITY control input	$T_{GCCK\_}RPOL/T_{GCKC\_}RPOL$	0.02/ 0.00	0.02/ 0.00	0.02/ 0.00	ns, min
ENCHANSYNC control input	$T_{GCCK\_}ECSY/T_{GCKC\_}ECSY$	0.02/ 0.00	0.02/ 0.00	0.02/ 0.00	ns, min
Clock to Out					
RXNOTINTABLE status outputs	$T_{GCKST\_}RNIT$	0.50	0.50	0.55	ns, max
RXDISPERR status outputs	$T_{GCKST\_}RDERR$	0.50	0.50	0.55	ns, max
RXCHARISCOMMA status outputs	$T_{GCKST\_}RCMCH$	0.50	0.50	0.55	ns, max
RXREALIGN status output	$T_{GCKST\_}ALIGN$	0.41	0.41	0.46	ns, max
RXCOMMADET status output	$T_{GCKST\_}CMDT$	0.41	0.41	0.46	ns, max
RXLOSSOFSYNC status outputs	$T_{GCKST\_}RLOS$	0.50	0.50	0.55	ns, max
RXCLKCORCNT status outputs	$T_{GCKST\_}RCCCNT$	0.41	0.41	0.46	ns, max

IOB Output Switching Characteristics Standard Adjustments

Table 38 gives all standard-specific adjustments for output delays terminating at pads, based on standard capacitive load, C_{REF}. Output delays terminating at a pad are specified for LVCMOS25 with 12 mA drive and fast slew rate. For other standards, adjust the delays by the values shown.

Table 38: **IOB Output Switching Characteristics Standard Adjustments**

Description	IOSTANDARD Attribute	Timing Parameter	Speed Grade			Units
			-7	-6	-5	
LVTTL (Low-Voltage Transistor-Transistor Logic), Slow, 2 mA	LVTTL_S2	T_{OLVTTL_S2}	5.42	6.24	6.86	ns
LVTTL, Slow, 4 mA	LVTTL_S4	T_{OLVTTL_S4}	3.09	3.55	3.91	ns
LVTTL, Slow, 6 mA	LVTTL_S6	T_{OLVTTL_S6}	2.26	2.60	2.86	ns
LVTTL, Slow, 8 mA	LVTTL_S8	T_{OLVTTL_S8}	1.47	1.69	1.86	ns
LVTTL, Slow, 12 mA	LVTTL_S12	T_{OLVTTL_S12}	1.02	1.18	1.29	ns
LVTTL, Slow, 16 mA	LVTTL_S16	T_{OLVTTL_S16}	0.46	0.53	0.58	ns
LVTTL, Slow, 24 mA	LVTTL_S24	T_{OLVTTL_S24}	0.37	0.42	0.47	ns
LVTTL, Fast, 2 mA	LVTTL_F2	T_{OLVTTL_F2}	4.42	5.09	5.59	ns
LVTTL, Fast, 4 mA	LVTTL_F4	T_{OLVTTL_F4}	1.95	2.24	2.46	ns
LVTTL, Fast, 6 mA	LVTTL_F6	T_{OLVTTL_F6}	1.10	1.26	1.39	ns
LVTTL, Fast, 8 mA	LVTTL_F8	T_{OLVTTL_F8}	0.40	0.46	0.51	ns
LVTTL, Fast, 12 mA	LVTTL_F12	T_{OLVTTL_F12}	0.24	0.27	0.30	ns
LVTTL, Fast, 16 mA	LVTTL_F16	T_{OLVTTL_F16}	0.05	0.06	0.07	ns
LVTTL, Fast, 24 mA	LVTTL_F24	T_{OLVTTL_F24}	–0.01	–0.01	–0.01	ns
LVCMOS (Low-Voltage CMOS), 3.3V, Slow, 2 mA	LVCMOS33_S2	$T_{OLVCMOS33\_S2}$	5.42	6.23	6.86	ns
LVCMOS, 3.3V, Slow, 4 mA	LVCMOS33_S4	$T_{OLVCMOS33\_S4}$	3.14	3.61	3.97	ns
LVCMOS, 3.3V, Slow, 6 mA	LVCMOS33_S6	$T_{OLVCMOS33\_S6}$	2.26	2.60	2.86	ns
LVCMOS, 3.3V, Slow, 8 mA	LVCMOS33_S8	$T_{OLVCMOS33\_S8}$	1.47	1.69	1.86	ns
LVCMOS, 3.3V, Slow, 12 mA	LVCMOS33_S12	$T_{OLVCMOS33\_S12}$	1.03	1.18	1.30	ns
LVCMOS, 3.3V, Slow, 16 mA	LVCMOS33_S16	$T_{OLVCMOS33\_S16}$	0.45	0.52	0.57	ns
LVCMOS, 3.3V, Slow, 24 mA	LVCMOS33_S24	$T_{OLVCMOS33\_S24}$	0.39	0.44	0.49	ns
LVCMOS, 3.3V, Fast, 2 mA	LVCMOS33_F2	$T_{OLVCMOS33\_F2}$	4.46	5.13	5.64	ns
LVCMOS, 3.3V, Fast, 4 mA	LVCMOS33_F4	$T_{OLVCMOS33\_F4}$	1.96	2.25	2.48	ns
LVCMOS, 3.3V, Fast, 6 mA	LVCMOS33_F6	$T_{OLVCMOS33\_F6}$	1.11	1.28	1.40	ns
LVCMOS, 3.3V, Fast, 8 mA	LVCMOS33_F8	$T_{OLVCMOS33\_F8}$	0.41	0.47	0.52	ns
LVCMOS, 3.3V, Fast, 12 mA	LVCMOS33_F12	$T_{OLVCMOS33\_F12}$	0.23	0.26	0.28	ns
LVCMOS, 3.3V, Fast, 16 mA	LVCMOS33_F16	$T_{OLVCMOS33\_F16}$	0.02	0.02	0.03	ns
LVCMOS, 3.3V, Fast, 24 mA	LVCMOS33_F24	$T_{OLVCMOS33\_F24}$	–0.07	–0.08	–0.09	ns
LVCMOS, 2.5V, Slow, 2 mA	LVCMOS25_S2	$T_{OLVCMOS25\_S2}$	4.12	4.74	5.21	ns
LVCMOS, 2.5V, Slow, 4 mA	LVCMOS25_S4	$T_{OLVCMOS25\_S4}$	2.43	2.80	3.07	ns
LVCMOS, 2.5V, Slow, 6 mA	LVCMOS25_S6	$T_{OLVCMOS25\_S6}$	1.76	2.02	2.22	ns
LVCMOS, 2.5V, Slow, 8 mA	LVCMOS25_S8	$T_{OLVCMOS25\_S8}$	1.04	1.19	1.31	ns
LVCMOS, 2.5V, Slow, 12 mA	LVCMOS25_S12	$T_{OLVCMOS25\_S12}$	0.76	0.87	0.96	ns
LVCMOS, 2.5V, Slow, 16 mA	LVCMOS25_S16	$T_{OLVCMOS25\_S16}$	0.41	0.47	0.52	ns
LVCMOS, 2.5V, Slow, 24 mA	LVCMOS25_S24	$T_{OLVCMOS25\_S24}$	0.23	0.26	0.28	ns
LVCMOS, 2.5V, Fast, 2 mA	LVCMOS25_F2	$T_{OLVCMOS25\_F2}$	3.29	3.78	4.16	ns
LVCMOS, 2.5V, Fast, 4 mA	LVCMOS25_F4	$T_{OLVCMOS25\_F4}$	1.31	1.50	1.65	ns

Block SelectRAM+ Switching Characteristics

Table 47: **Block SelectRAM+ Switching Characteristics**

Description	Symbol	Speed Grade			Units
		-7	-6	-5	
Sequential Delays					
Clock CLK to DOUT output	T_{BCKO}	1.41	1.50	1.68	ns, max
Setup and Hold Times Before Clock CLK					
ADDR inputs	T_{BACK}/T_{BCKA}	0.27/ 0.22	0.31/ 0.25	0.35/ 0.28	ns, min
DIN inputs	T_{BDCK}/T_{BCKD}	0.20/ 0.22	0.23/ 0.25	0.26/ 0.28	ns, min
EN input	T_{BECK}/T_{BCKE}	0.28/ 0.00	0.32/ 0.00	0.35/ 0.00	ns, min
RST input	T_{BRCK}/T_{BCKR}	0.28/ 0.00	0.32/ 0.00	0.35/ 0.00	ns, min
WEN input	T_{BWCK}/T_{BCKW}	0.33/ 0.00	0.35/ 0.00	0.39/ 0.00	ns, min
Clock CLK					
CLKA to CLKB setup time for different ports	T_{BCCS}	1.0	1.0	1.0	ns, min
Minimum Pulse Width, High	T_{BPWH}	1.17	1.30	1.50	ns, min
Minimum Pulse Width, Low	T_{BPWL}	1.17	1.30	1.50	ns, min

Notes:
1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.

TBUF Switching Characteristics

Table 48: **TBUF Switching Characteristics**

Description	Symbol	Speed Grade			Units
		-7	-6	-5	
Combinatorial Delays					
IN input to OUT output	T_{IO}	0.88	1.01	1.12	ns, max
TRI input to OUT output high-impedance	T_{OFF}	0.48	0.55	0.61	ns, max
TRI input to valid data on OUT output	T_{ON}	0.48	0.55	0.61	ns, max

Input Clock Tolerances

Table 58: **Input Clock Tolerances**

Description	Symbol	Constraints F_{CLKIN}	Speed Grade						Units
			–7		–6		–5		
			Min	Max	Min	Max	Min	Max	
Input Clock Low/High Pulse Width									
PSCLK	PSCLK_PULSE	< 1MHz	25.00		25.00		25.00		ns
PSCLK and CLKIN(3)	PSCLK_PULSE and CLKIN_PULSE	1 – 10 MHz	25.00		25.00		25.00		ns
		10 – 25 MHz	10.00		10.00		10.00		ns
		25 – 50 MHz	5.00		5.00		5.00		ns
		50 – 100 MHz	3.00		3.00		3.00		ns
		100 – 150 MHz	2.40		2.40		2.40		ns
		150 – 200 MHz	2.00		2.00		2.00		ns
		200 – 250 MHz	1.80		1.80		1.80		ns
		250 – 300 MHz	1.50		1.50		1.50		ns
		300 – 350 MHz	1.30		1.30		1.30		ns
		350 – 400 MHz	1.15		1.15		1.15		ns
		> 400 MHz	1.05		1.05		1.05		ns
Input Clock Cycle-Cycle Jitter (Low Frequency Mode)									
CLKIN (using DLL outputs)(1)	CLKIN_CYC_JITT_DLL_LF			±300		±300		±300	ps
CLKIN (using CLKFX outputs)(2)	CLKIN_CYC_JITT_FX_LF			±300		±300		±300	ps
Input Clock Cycle-Cycle Jitter (High Frequency Mode)									
CLKIN (using DLL outputs)(1)	CLKIN_CYC_JITT_DLL_HF			±150		±150		±150	ps
CLKIN (using CLKFX outputs)(2)	CLKIN_CYC_JITT_FX_HF			±150		±150		±150	ps
Input Clock Period Jitter (Low Frequency Mode)									
CLKIN (using DLL outputs)(1)	CLKIN_PER_JITT_DLL_LF			±1		±1		±1	ns
CLKIN (using CLKFX outputs)(2)	CLKIN_PER_JITT_FX_LF			±1		±1		±1	ns
Input Clock Period Jitter (High Frequency Mode)									
CLKIN (using DLL outputs)(1)	CLKIN_PER_JITT_DLL_HF			±1		±1		±1	ns
CLKIN (using CLKFX outputs)(2)	CLKIN_PER_JITT_FX_HF			±1		±1		±1	ns
Feedback Clock Path Delay Variation									
CLKFB off-chip feedback	CLKFB_DELAY_VAR_EXT			±1		±1		±1	ns

Notes:
1. "DLL outputs" is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. If both DLL and CLKFX outputs are used, follow the more restrictive specification.
3. If DCM phase shift feature is used and CLKIN frequency > 200 Mhz, CLKIN duty cycle must be within ±5% (45/55 to 55/45).

Source-Synchronous Switching Characteristics

The parameters in this section provide the necessary values for calculating timing budgets for Virtex-II Pro source-synchronous transmitter and receiver data-valid windows.

Table 64: **Duty Cycle Distortion and Clock-Tree Skew**

Description	Symbol	Device	Speed Grade			Units
			–7	–6	–5	
Duty Cycle Distortion(1)	T_{DCD_LOCAL}	All	0.10	0.10	0.20	ns
	T_{DCD_CLK180}		0.10	0.11	0.13	ns
Clock Tree Skew(2)	T_{CKSKEW}	XC2VP2	0.13	0.13	0.13	ns
		XC2VP4	0.13	0.13	0.13	ns
		XC2VP7	0.13	0.13	0.13	ns
		XC2VP20	0.20	0.21	0.22	ns
		XC2VPX20	0.20	0.21	0.22	ns
		XC2VP30	0.20	0.22	0.24	ns
		XC2VP40	0.33	0.34	0.35	ns
		XC2VP50	0.40	0.41	0.42	ns
		XC2VP70	0.54	0.59	0.64	ns
		XC2VPX70	0.54	0.59	0.64	ns
		XC2VP100	N/A	0.79	0.87	ns

Notes:

1. These parameters represent the worst-case duty cycle distortion observable at the pins of the device using LVDS output buffers. For cases where other I/O standards are used, IBIS can be used to calculate any additional duty cycle distortion that might be caused by asymmetrical rise/fall times.

   T_{DCD_LOCAL} applies to cases where the dedicated path from the DCM to the BUFG is bypassed and where local (IOB) inversion is used to provide the negative-edge clock to the DDR element in the I/O. Users must follow the implementation guidelines contained in **XAPP685** for these specifications to apply.

   T_{DCD_CLK180} applies to cases where the CLK180 output of the DCM is used to provide the negative-edge clock to the DDR element in the I/O.
2. This value represents the worst-case clock-tree skew observable between sequential I/O elements. Significantly less clock-tree skew exists for I/O registers that are close to each other and fed by the same or adjacent clock-tree branches. Use the Xilinx FPGA_Editor and Timing Analyzer tools to evaluate clock skew specific to your application.

Date	Version	Revision
08/25/03	2.9	• Updated time and frequency parameters as per speedsfile **v1.81**. • Table 1: Footnote (2) rewritten to specify “one or more banks.” • Table 2: Added footnote referring to XAPP659 for 3.3V I/O operation. • Table 53 and Table 54: Revised test setup footnote to refer to Figure 6. Previously specified a capacitive load parameter. • Table 57: Due to a document compilation error in v2.8, some DCM parameters were erroneously omitted from the full data sheet file (all four modules concatenated), though not from the stand-alone Module 3 file. The omitted parameters have been restored. • Table 64 and Table 66: Corrected parameters to expression in picoseconds, as labeled. Previously expressed in nanoseconds, but labeled picoseconds. • Figure 6: Added note to figure regarding termination resistors. • Table 5: Added $I_{CCINTMIN}$ for XC2VP30 device.
09/10/03	2.10	• Figure 7: Changed representation of mode pins M0, M1, and M2 indicating that they must be held to a constant DC level during and after configuration. • Table 49: Added footnote indicating that mode pins M0, M1, and M2 must be held to a constant DC level during and after configuration.
10/14/03	2.11	• Table 1: Deleted Footnote (2), which had derated the absolute maximum T_J when one or more banks operated at 3.3V. Changed T_J description from “Operating junction temperature” to “Maximum junction temperature”. Added new Footnote (2) linking to website for package thermal data. • Table 4 and Table 5: Filled in power-on and quiescent current parameters for all devices through XC2VP70. Added Industrial Grade multiplier specification to Footnote (1) in both tables. • In section General Power Supply Requirements, replaced reference to Answer Record 11713 with reference to **XAPP689** regarding handling of simultaneously switching outputs (SSO). • In section I/O Standard Adjustment Measurement Methodology: - Table 39 renamed Input Delay Measurement Methodology. Added footnotes. - Added new Table 40, Output Delay Measurement Methodology. - Replaced Figure 6, Generalized Test Setup, with new drawing. - Revised and extended text describing output delay measurement procedure. • Table 58: For Input Clock Low/High Pulse Width, PSCLK and CLKIN, changed existing Footnote (2) to new Footnote (3).
11/10/03	2.12	• Table 1: Changed 3.3V absolute max V_{IN} and V_{TS} from 3.75V to 4.05V. Added footnote referring to **XAPP659**. • Table 4: Removed MIN column from table.
12/05/03	3.0	• XC2VP2 through XC2VP70 speed grades -5, -6, and -7, and XC2VP100 speed grades -5 and -6, updated and released to **Production status** as per speedsfile **v1.83**. Featured changes: - Speedsfile parameter values for -7 speed grade added for devices XC2VP2-XC2VP70. - Table 13 and Table 14: Pin-to-pin and register-to_register performance parameter values added. - Table 64: New parameter T_{DCD_LOCAL} (and footnote) replaces T_{DCD_CLK0}. - All remaining source-synchronous parameter values added (Table 64 & following).

FG256/FGG256 Fine-Pitch BGA Package

As shown in Table 5, XC2VP2 and XC2VP4 Virtex-II Pro devices are available in the FG256/FGG256 fine-pitch BGA package. The pins in each of these devices are identical. Following this table are the FG256/FGG256 Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 5: **FG256/FGG256 — XC2VP2 and XC2VP4**

Bank	Pin Description	Pin Number
0	IO_L01N_0/VRP_0	C2
0	IO_L01P_0/VRN_0	C3
0	IO_L02N_0	B3
0	IO_L02P_0	C4
0	IO_L03N_0	A2
0	IO_L03P_0/VREF_0	A3
0	IO_L06N_0	D5
0	IO_L06P_0	C5
0	IO_L07P_0	D6
0	IO_L09N_0	E6
0	IO_L09P_0/VREF_0	E7
0	IO_L69N_0	D7
0	IO_L69P_0/VREF_0	C7
0	IO_L74N_0/GCLK7P	D8
0	IO_L74P_0/GCLK6S	C8
0	IO_L75N_0/GCLK5P	B8
0	IO_L75P_0/GCLK4S	A8
1	IO_L75N_1/GCLK3P	A9
1	IO_L75P_1/GCLK2S	B9
1	IO_L74N_1/GCLK1P	C9
1	IO_L74P_1/GCLK0S	D9
1	IO_L69N_1/VREF_1	C10
1	IO_L69P_1	D10
1	IO_L09N_1/VREF_1	E10
1	IO_L09P_1	E11
1	IO_L07N_1	D11
1	IO_L06N_1	C12
1	IO_L06P_1	D12
1	IO_L03N_1/VREF_1	A14
1	IO_L03P_1	A15

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
N/A	RSVD	C23			
N/A	VBATT	A24			
N/A	TMS	B24			
N/A	TCK	B26			
N/A	TDO	D24			
N/A	CCLK	AE24			
N/A	PWRDWN_B	AF24			
N/A	DONE	AD23			
N/A	AVCCAUXRX16	AE23			
N/A	VTRXPAD16	AE22			
N/A	RXNPAD16	AF23			
N/A	RXPPAD16	AF22			
N/A	GNDA16	AD21			
N/A	TXPPAD16	AF21			
N/A	TXNPAD16	AF20			
N/A	VTTXPAD16	AE20			
N/A	AVCCAUXTX16	AE21			
N/A	AVCCAUXRX18	AE18			
N/A	VTRXPAD18	AE17			
N/A	RXNPAD18	AF18			
N/A	RXPPAD18	AF17			
N/A	GNDA18	AD16			
N/A	TXPPAD18	AF16			
N/A	TXNPAD18	AF15			
N/A	VTTXPAD18	AE15			
N/A	AVCCAUXTX18	AE16			
N/A	AVCCAUXRX19	AE12			
N/A	VTRXPAD19	AE11			
N/A	RXNPAD19	AF12			
N/A	RXPPAD19	AF11			
N/A	GNDA19	AD11			
N/A	TXPPAD19	AF10			
N/A	TXNPAD19	AF9			
N/A	VTTXPAD19	AE9			
N/A	AVCCAUXTX19	AE10			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
5	IO_L74P_5/GCLK4P	AB14			
5	IO_L73N_5	AA14			
5	IO_L73P_5	Y14			
5	IO_L69N_5/VREF_5	W14			
5	IO_L69P_5	W15			
5	IO_L68N_5	AD15			
5	IO_L68P_5	AC15			
5	IO_L67N_5	AB15			
5	IO_L67P_5	AA15			
5	IO_L45N_5/VREF_5	AC16	NC	NC	
5	IO_L45P_5	AB16	NC	NC	
5	IO_L44N_5	Y15	NC	NC	
5	IO_L44P_5	Y16	NC	NC	
5	IO_L43N_5	AC17	NC	NC	
5	IO_L43P_5	AB17	NC	NC	
5	IO_L39N_5	AA16	NC	NC	
5	IO_L39P_5	AA17	NC	NC	
5	IO_L38N_5	W16	NC	NC	
5	IO_L38P_5	Y17	NC	NC	
5	IO_L37N_5	AD18	NC	NC	
5	IO_L37P_5	AC18	NC	NC	
5	IO_L09N_5/VREF_5	AA18			
5	IO_L09P_5	Y18			
5	IO_L08N_5	AF19			
5	IO_L08P_5	AE19			
5	IO_L07N_5/VREF_5	AD19			
5	IO_L07P_5	AC19			
5	IO_L06N_5/VRP_5	AB18			
5	IO_L06P_5/VRN_5	AB19			
5	IO_L05_5/No_Pair	Y19			
5	IO_L03N_5/D4	AA19			
5	IO_L03P_5/D5	AA20			
5	IO_L02N_5/D6	AC20			
5	IO_L02P_5/D7	AB20			
5	IO_L01N_5/RDWR_B	AD21			
5	IO_L01P_5/CS_B	AC21			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
6	IO_L52N_6	U22	NC		
6	IO_L53P_6	U23	NC		
6	IO_L53N_6	U24	NC		
6	IO_L54P_6	V26	NC		
6	IO_L54N_6	U26	NC		
6	IO_L55P_6	U20	NC		
6	IO_L55N_6	T19	NC		
6	IO_L56P_6	T20	NC		
6	IO_L56N_6	R20	NC		
6	IO_L57P_6	T21	NC		
6	IO_L57N_6/VREF_6	T22	NC		
6	IO_L58P_6	T23	NC		
6	IO_L58N_6	T24	NC		
6	IO_L59P_6	T25	NC		
6	IO_L59N_6	T26	NC		
6	IO_L60P_6	R19	NC		
6	IO_L60N_6	P19	NC		
6	IO_L85P_6	R21			
6	IO_L85N_6	R22			
6	IO_L86P_6	R23			
6	IO_L86N_6	R24			
6	IO_L87P_6	R25			
6	IO_L87N_6/VREF_6	R26			
6	IO_L88P_6	P20			
6	IO_L88N_6	P21			
6	IO_L89P_6	P22			
6	IO_L89N_6	P23			
6	IO_L90P_6	P24			
6	IO_L90N_6	P25			
7	IO_L90P_7	N25			
7	IO_L90N_7	N24			
7	IO_L89P_7	N23			
7	IO_L89N_7	N22			
7	IO_L88P_7	N21			
7	IO_L88N_7/VREF_7	N20			
7	IO_L87P_7	M26			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
2	IO_L41N_2		L8	NC		
2	IO_L41P_2		L7	NC		
2	IO_L42N_2		H4	NC		
2	IO_L42P_2		H3	NC		
2	IO_L43N_2		H2			
2	IO_L43P_2		J2			
2	IO_L44N_2		M8			
2	IO_L44P_2		M7			
2	IO_L45N_2		K6			
2	IO_L45P_2		K5			
2	IO_L46N_2/VREF_2		J1			
2	IO_L46P_2		K1			
2	IO_L47N_2		M6			
2	IO_L47P_2		M5			
2	IO_L48N_2		J4			
2	IO_L48P_2		J3			
2	IO_L49N_2		K2			
2	IO_L49P_2		L2			
2	IO_L50N_2		N8			
2	IO_L50P_2		N7			
2	IO_L51N_2		K4			
2	IO_L51P_2		K3			
2	IO_L52N_2/VREF_2		L1			
2	IO_L52P_2		M1			
2	IO_L53N_2		N6			
2	IO_L53P_2		N5			
2	IO_L54N_2		L5			
2	IO_L54P_2		L4			
2	IO_L55N_2		M2			
2	IO_L55P_2		N2			
2	IO_L56N_2		P9			
2	IO_L56P_2		R9			
2	IO_L57N_2		M4			
2	IO_L57P_2		M3			
2	IO_L58N_2/VREF_2		N1			
2	IO_L58P_2		P1			

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
2	VCCO_2	F8		
2	VCCO_2	U7		
2	VCCO_2	Y5		
2	VCCO_2	N4		
2	VCCO_2	J4		
2	VCCO_2	E4		
2	VCCO_2	U3		
2	VCCO_2	E1		
1	VCCO_1	N14		
1	VCCO_1	K13		
1	VCCO_1	F13		
1	VCCO_1	P19		
1	VCCO_1	P18		
1	VCCO_1	P17		
1	VCCO_1	K17		
1	VCCO_1	F17		
1	VCCO_1	P16		
1	VCCO_1	N16		
1	VCCO_1	P15		
1	VCCO_1	N15		
0	VCCO_0	K27		
0	VCCO_0	F27		
0	VCCO_0	N26		
0	VCCO_0	P25		
0	VCCO_0	N25		
0	VCCO_0	P24		
0	VCCO_0	N24		
0	VCCO_0	P23		
0	VCCO_0	K23		
0	VCCO_0	F23		
0	VCCO_0	P22		
0	VCCO_0	P21		
N/A	CCLK	AJ10		
N/A	PROG_B	D32		
N/A	DONE	AJ11		
N/A	M0	AP31		
N/A	M1	AJ30		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
2	IO_L08P_2		K5		
2	IO_L09N_2		K8		
2	IO_L09P_2		K7		
2	IO_L10N_2/VREF_2		K2		
2	IO_L10P_2		K1		
2	IO_L11N_2		L8		
2	IO_L11P_2		L9		
2	IO_L12N_2		L6		
2	IO_L12P_2		L7		
2	IO_L13N_2		K3		
2	IO_L13P_2		L3		
2	IO_L14N_2		L5		
2	IO_L14P_2		L4		
2	IO_L15N_2		L1		
2	IO_L15P_2		L2		
2	IO_L16N_2/VREF_2		M7		
2	IO_L16P_2		M8		
2	IO_L17N_2		M11		
2	IO_L17P_2		M12		
2	IO_L18N_2		M9		
2	IO_L18P_2		M10		
2	IO_L19N_2		M2		
2	IO_L19P_2		M3		
2	IO_L20N_2		M4		
2	IO_L20P_2		M5		
2	IO_L21N_2		N7		
2	IO_L21P_2		N8		
2	IO_L22N_2/VREF_2		N5		
2	IO_L22P_2		N6		
2	IO_L23N_2		N9		
2	IO_L23P_2		N10		
2	IO_L24N_2		N3		
2	IO_L24P_2		N4		
2	IO_L25N_2		N1		
2	IO_L25P_2		N2		
2	IO_L26N_2		N11		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	TXPPAD7		A20		
N/A	GNDA7		C21		
N/A	RXPPAD7		A19		
N/A	RXNPAD7		A18		
N/A	VTRXPAD7		B19		
N/A	AVCCAUXRX7		B18		
N/A	AVCCAUXTX8		B16		
N/A	VTTXPAD8		B17		
N/A	TXNPAD8		A17		
N/A	TXPPAD8		A16		
N/A	GNDA8		C16		
N/A	RXPPAD8		A15		
N/A	RXNPAD8		A14		
N/A	VTRXPAD8		B15		
N/A	AVCCAUXRX8		B14		
N/A	AVCCAUXTX9		B12		
N/A	VTTXPAD9		B13		
N/A	TXNPAD9		A13		
N/A	TXPPAD9		A12		
N/A	GNDA9		C12		
N/A	RXPPAD9		A11		
N/A	RXNPAD9		A10		
N/A	VTRXPAD9		B11		
N/A	AVCCAUXRX9		B10		
N/A	AVCCAUXTX10		B8		
N/A	VTTXPAD10		B9		
N/A	TXNPAD10		A9		
N/A	TXPPAD10		A8		
N/A	GNDA10		C8		
N/A	RXPPAD10		A7		
N/A	RXNPAD10		A6		
N/A	VTRXPAD10		B7		
N/A	AVCCAUXRX10		B6		
N/A	AVCCAUXTX11		B4		
N/A	VTTXPAD11		B5		
N/A	TXNPAD11		A5		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
2	IO_L75N_2	C5	
2	IO_L75P_2	B5	
2	IO_L76N_2/VREF_2	D7	
2	IO_L76P_2	C6	
2	IO_L77N_2	H8	
2	IO_L77P_2	H9	
2	IO_L78N_2	C3	
2	IO_L78P_2	C4	
2	IO_L79N_2	D1	
2	IO_L79P_2	D2	
2	IO_L80N_2	J8	
2	IO_L80P_2	K9	
2	IO_L81N_2	E6	
2	IO_L81P_2	D5	
2	IO_L82N_2/VREF_2	E4	
2	IO_L82P_2	D4	
2	IO_L83N_2	L8	
2	IO_L83P_2	L9	
2	IO_L84N_2	E3	
2	IO_L84P_2	D3	
2	IO_L61N_2	F8	
2	IO_L61P_2	E8	
2	IO_L62N_2	M8	
2	IO_L62P_2	M9	
2	IO_L63N_2	F7	
2	IO_L63P_2	E7	
2	IO_L64N_2/VREF_2	F3	
2	IO_L64P_2	E2	
2	IO_L65N_2	N12	
2	IO_L65P_2	P12	
2	IO_L66N_2	F1	
2	IO_L66P_2	F2	
2	IO_L67N_2	G7	
2	IO_L67P_2	G8	
2	IO_L68N_2	N10	
2	IO_L68P_2	N11	
2	IO_L69N_2	G6	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
2	IO_L22N_2/VREF_2	L4	
2	IO_L22P_2	L5	
2	IO_L23N_2	T8	
2	IO_L23P_2	T9	
2	IO_L24N_2	L3	
2	IO_L24P_2	K3	
2	IO_L25N_2	L1	
2	IO_L25P_2	L2	
2	IO_L26N_2	U12	
2	IO_L26P_2	V12	
2	IO_L27N_2	M7	
2	IO_L27P_2	L6	
2	IO_L28N_2/VREF_2	M5	
2	IO_L28P_2	M6	
2	IO_L29N_2	U10	
2	IO_L29P_2	U11	
2	IO_L30N_2	M3	
2	IO_L30P_2	M4	
2	IO_L31N_2	N6	
2	IO_L31P_2	N7	
2	IO_L32N_2	U7	
2	IO_L32P_2	U8	
2	IO_L33N_2	N3	
2	IO_L33P_2	N4	
2	IO_L34N_2/VREF_2	N2	
2	IO_L34P_2	M2	
2	IO_L35N_2	V10	
2	IO_L35P_2	V11	
2	IO_L36N_2	P6	
2	IO_L36P_2	P7	
2	IO_L37N_2	P1	
2	IO_L37P_2	P2	
2	IO_L38N_2	V8	
2	IO_L38P_2	V9	
2	IO_L39N_2	R6	
2	IO_L39P_2	P5	
2	IO_L40N_2/VREF_2	R4	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
6	IO_L02P_6	BA34	
6	IO_L02N_6	AY34	
6	IO_L03P_6	BB37	
6	IO_L03N_6/VREF_6	BA37	
6	IO_L04P_6	BB36	
6	IO_L04N_6	BA36	
6	IO_L05P_6	AW34	
6	IO_L05N_6	AW35	
6	IO_L06P_6	BB35	
6	IO_L06N_6	BA35	
6	IO_L73P_6	BA38	
6	IO_L73N_6	AY38	
6	IO_L74P_6	AU34	
6	IO_L74N_6	AT34	
6	IO_L75P_6	AY39	
6	IO_L75N_6/VREF_6	AY40	
6	IO_L76P_6	AY37	
6	IO_L76N_6	AW36	
6	IO_L77P_6	AR34	
6	IO_L77N_6	AR35	
6	IO_L78P_6	AY35	
6	IO_L78N_6	AY36	
6	IO_L79P_6	AW41	
6	IO_L79N_6	AW42	
6	IO_L80P_6	AP35	
6	IO_L80N_6	AN34	
6	IO_L81P_6	AW40	
6	IO_L81N_6/VREF_6	AV40	
6	IO_L82P_6	AW39	
6	IO_L82N_6	AV39	
6	IO_L83P_6	AM34	
6	IO_L83N_6	AM35	
6	IO_L84P_6	AW38	
6	IO_L84N_6	AV37	
6	IO_L61P_6	AV41	
6	IO_L61N_6	AU40	
6	IO_L62P_6	AL34	